

ABSTRACT

The present invention provides an adhesive sheet which sufficiently and stably adheres to the back surface of a lead frame and the back surface of a sealing resin without peeling off therefrom, before the releasing step, even under heat hysteresis accompanying assembling of the QFN, which does not exhibit leakage of the sealing resin, which can be easily released in the releasing step, and which does not cause an adhesive residue or breakage, and also provides a method of producing a semiconductor device using the same. In an adhesive sheet for producing a semiconductor device which includes a substrate, and a thermo-setting type adhesive layer provided on one surface of the substrate mentioned above, and which is releasably adhered to a wiring substrate or a lead frame of the semiconductor device, the adhesive layer mentioned above contains (a) a carboxyl group-containing acrylonitrile – butadiene copolymer, (b) an epoxy resin having the following structural formula (1), and (c) a compound having two or more maleimide groups, wherein a residual amount of unreacted maleimide ranges from 0.02 to 0.13.

